

## **Kulicke & Soffa Expands the Advanced Copper Solution (ACS) Series Capillaries - Introduces ACS Max™ and ACS Lite™**

SINGAPORE--(BUSINESS WIRE)-- Kulicke and Soffa Industries, Inc. (NASDAQ: KLIC) ("Kulicke & Soffa", "K&S" or the "Company") today announced the expansion of its Advanced Copper Solution (ACS) Series Capillaries, with the addition of ACS Max™ and ACS Lite™.

The ACS Series of capillaries are based on the Company's advanced material development and deep-rooted application knowledge. This family of capillaries offers production benefits for various copper wire bonding applications and has been expanded to serve the broader copper market:

- The ACS Pro™, first launched at SEMICON Taiwan in Sept of 2013, is the best fit for ultra-fine pitch and advanced copper wire bonding applications with a bond pad pitch range of 40-69 microns.
- The new ACS Max™ is targeted for advanced package carrier families, such as mid-pin count QFP, QFN, PPF, uPPF and leadframes with a bond pad pitch range of 70-120 microns.
- The new ACS Lite™ is targeted for low-pin count applications, such as discrete & powered integrated circuit applications using large wire diameters and a bond pad pitch in excess of 120 microns.

Nelson Wong, Kulicke & Soffa's Vice President, Wire Bond Solutions Business Unit, remarked, "Aligned with our leading position in copper wire bonding, the introduction of ACS Max™ and ACS Lite™ further enhances our customer's ability to create high quality bonds using larger diameter copper wire. The unique design dynamics of the ACS Series drive cost of ownership benefits by enabling a wider process window and more consistent bond quality throughout the capillary's life."

The ACS Max™ and ACS Lite™ Capillaries will debut at the SEMICON China show at the Shanghai New International Expo Centre, Booth #3417, from March 18-20, 2014.

### About Kulicke & Soffa

Kulicke & Soffa (NASDAQ: KLIC) is a global leader in the design and manufacture of semiconductor and LED assembly equipment. As a pioneer in this industry, K&S has provided customers with market leading packaging solutions for decades. In recent years, K&S has expanded its product offerings through strategic acquisitions, adding wedge bonding and a broader range of expendable tools to its core ball bonding products. Combined with its extensive expertise in process technology, K&S is well positioned to help customers meet the challenges of assembling the next-generation semiconductor and LED devices. ([www.kns.com](http://www.kns.com))

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